

3.3 V Zero Delay Buffer

Features

- Zero input-output propagation delay, adjustable by capacitive load on FBK input
- Multiple configurations
- Multiple low-skew outputs
- 10 MHz to 133 MHz operating range
- 90 ps typical peak cycle-to-cycle jitter at 15 pF, 66 MHz
- Space-saving 8-pin 150-mil SOIC package
- 3.3 V operation
- Industrial temperature available

Functional Description

The CY2304 is a 3.3 V zero delay buffer designed to distribute high-speed clocks in PC, workstation, datacom, telecom, and other high performance applications.

The part has an on-chip phase-locked loop (PLL) that locks to an input clock presented on the REF pin. The PLL feedback is required to be driven into the FBK pin, and can be obtained from

one of the outputs. The input-to-output skew is guaranteed to be less than 250 ps, and output-to-output skew is guaranteed to be less than 200 ps.

The CY2304 has two banks of two outputs each.

The CY2304 PLL enters a power down state when there are no rising edges on the REF input. In this mode, all outputs are three-stated and the PLL is turned off, resulting in less than 25 μ A of current draw.

Multiple CY2304 devices can accept the same input clock and distribute it in a system. In this case, the skew between the outputs of two devices is guaranteed to be less than 500 ps.

The CY2304 is available in two different configurations, as shown in [Table 1](#). The CY2304-1 is the base part, where the output frequencies equal the reference if there is no counter in the feedback path.

The CY2304-2 allows the user to obtain Ref and 1/2x or 2x frequencies on each output bank. The exact configuration and output frequencies depends on which output drives the feedback pin.

Logic Block Diagram

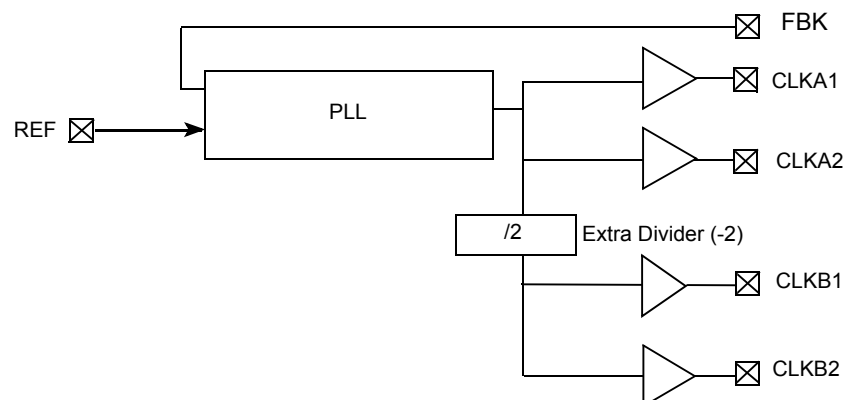


Table 1. Available Configurations

Device	FBK from	Bank A Frequency	Bank B Frequency
CY2304-1	Bank A or B	Reference	Reference
CY2304-2	Bank A	Reference	Reference/2
CY2304-2	Bank B	2 × Reference	Reference

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Pinout

Figure 1. 8-pin SOIC - Top View

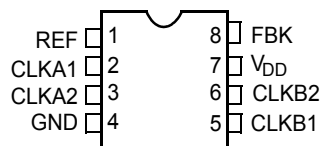


Table 2. Pin Definitions - 8-pin SOIC

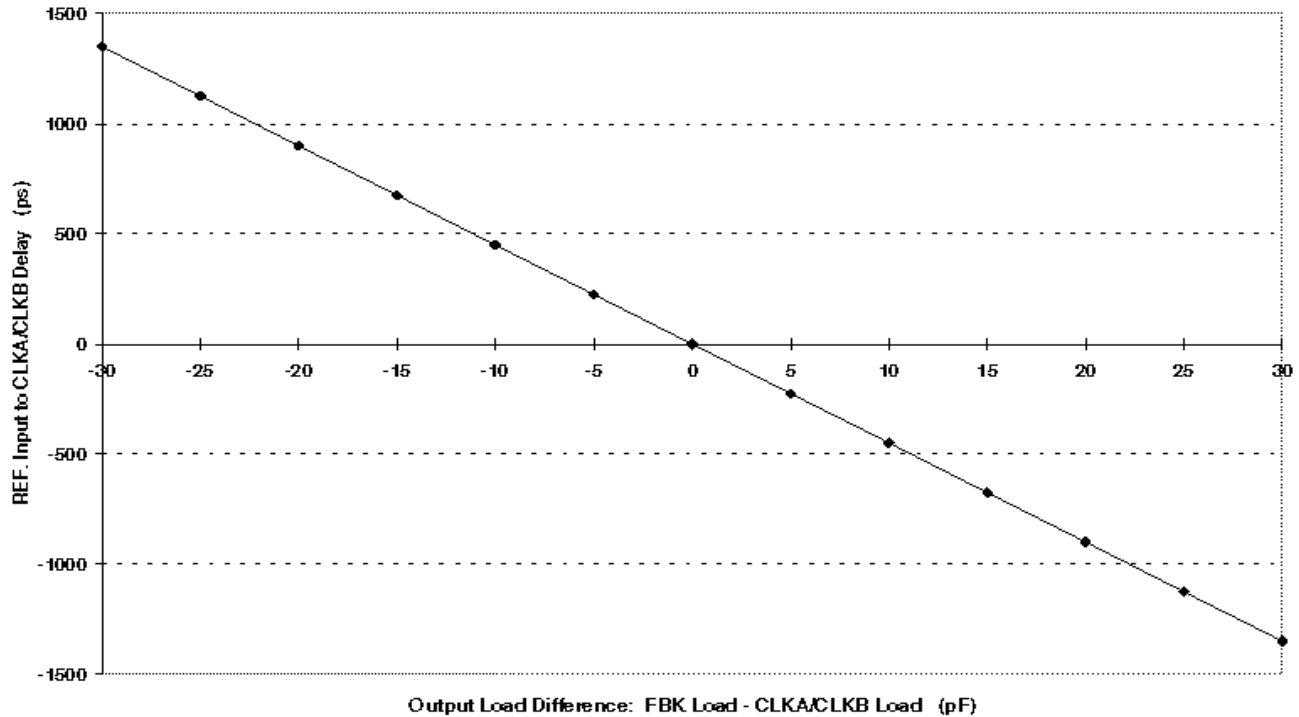
Pin	Signal	Description
1	REF ^[1]	Input reference frequency, 5-V tolerant input
2	CLKA1 ^[2]	Clock output, Bank A
3	CLKA2 ^[2]	Clock output, Bank A
4	GND	Ground
5	CLKB1 ^[2]	Clock output, Bank B
6	CLKB2 ^[2]	Clock output, Bank B
7	V _{DD}	3.3-V supply
8	FBK	PLL feedback input

Notes

1. Weak pull-down.
2. Weak pull-down on all outputs.

Zero Delay and Skew Control

Figure 2. REF. Input to CLKA/CLKB Delay vs. Difference in Loading Between FBK Pin and CLKA/CLKB Pins



To close the feedback loop of the CY2304, the FBK pin can be driven from any of the four available output pins. The output driving the FBK pin is driving a total load of 7 pF, with any additional load that it drives. The relative loading of this output (with respect to the remaining outputs) can adjust the input-output delay. This is shown in [Figure 2](#).

For applications requiring zero input-output delay, all outputs including the one providing feedback must be equally loaded. If input-output delay adjustments are required, use the graph shown in [Figure 2](#) to calculate loading differences between the feedback output and remaining outputs.

For zero output-output skew, be sure to load outputs equally. For further information on using CY2304, refer to the application note [AN1234](#) "CY2308: Zero Delay Buffer".

Maximum Ratings

Supply voltage to ground potential.....	–0.5 V to +7.0 V	Storage temperature	–65 °C to +150 °C
DC input voltage (except Ref).....	–0.5 V to $V_{DD} + 0.5$ V	Junction temperature	150 °C
DC input voltage REF.....	–0.5 V to 7 V	Static discharge voltage (per MIL-STD-883, Method 3015).....	> 2000 V

Operating Conditions for CY2304SXC Commercial Temperature Devices

Parameter	Description	Min	Max	Unit
V_{DD}	Supply voltage	3.0	3.6	V
T_A	Operating temperature (ambient temperature)	0	70	°C
C_L	Load capacitance (below 100 MHz)	–	30	pF
	Load capacitance (from 100 MHz to 133 MHz)	–	15	pF
C_{IN}	Input capacitance ^[3]	–	7	pF
t_{PU}	Power-up time for all V_{DD} s to reach minimum specified voltage (power ramps must be monotonic)	0.05	50	ms

Electrical Characteristics for CY2304SXC Commercial Temperature Devices

Parameter	Description	Test Conditions	Min	Max	Unit
V_{IL}	Input LOW voltage		–	0.8	V
V_{IH}	Input HIGH voltage		2.0	–	V
I_{IL}	Input LOW current	$V_{IN} = 0$ V	–	50.0	μA
I_{IH}	Input HIGH current	$V_{IN} = V_{DD}$	–	100.0	μA
V_{OL}	Output LOW voltage ^[4]	$I_{OL} = 8$ mA (–1, –2)	–	0.4	V
V_{OH}	Output HIGH voltage ^[4]	$I_{OH} = -8$ mA (–1, –2)	2.4	–	V
I_{DD} (PD mode)	Power-down supply current	REF = 0 MHz	–	12.0	μA
I_{DD}	Supply current	Unloaded outputs, 100 MHz REF, Select inputs at V_{DD} or GND	–	45.0	mA
		Unloaded outputs, 66 MHz REF (–1, –2)	–	32.0	mA
		Unloaded outputs, 33 MHz REF (–1, –2)	–	18.0	mA

Notes

- Applies to both REF clock and FBK.
- Parameter is guaranteed by design and characterization. Not 100% tested in production.

Switching Characteristics for CY2304SXC Commercial Temperature Devices

Parameter ^[5]	Name	Test Conditions	Min	Typ	Max	Unit
t_1	Output frequency	30 pF load, all devices	10	–	100	MHz
t_1	Output frequency	15 pF load, –1, –2 devices	10	–	133.3	MHz
t_{DC}	Duty cycle ^[6] = $t_2 \div t_1$ (–1, –2)	Measured at 1.4 V, $F_{OUT} = 66.66$ MHz, 30-pF load	40.0	50.0	60.0	%
t_{DC}	Duty cycle ^[6] = $t_2 \div t_1$ (–1, –2)	Measured at 1.4 V, $F_{OUT} < 50$ MHz, 15-pF load	45.0	50.0	55.0	%
t_3	Rise time ^[6] (–1, –2)	Measured between 0.8 V and 2.0 V, 30-pF load	–	–	2.20	ns
t_3	Rise time ^[6] (–1, –2)	Measured between 0.8 V and 2.0 V, 15-pF load	–	–	1.50	ns
t_4	Fall time ^[6] (–1, –2)	Measured between 0.8 V and 2.0 V, 30-pF load	–	–	2.20	ns
t_4	Fall time ^[6] (–1, –2)	Measured between 0.8 V and 2.0 V, 15 pF load	–	–	1.50	ns
t_5	Output-to-output skew on same Bank (–1, –2) ^[6]	All outputs equally loaded	–	–	200	ps
	Output bank A to output bank B skew (–1)	All outputs equally loaded	–	–	200	ps
	Output bank A to output bank B skew (–2)	All outputs equally loaded	–	–	400	ps
t_6	Skew, REF rising edge to FBK rising edge ^[6]	Measured at $V_{DD}/2$	–	0	± 250	ps
t_7	Device-to-device skew ^[6]	Measured at $V_{DD}/2$ on the FBK pins of devices	–	0	500	ps
t_J	Cycle-to-cycle jitter ^[6] (–1)	Measured at 66.67 MHz, loaded outputs, 15-pF load	–	90	175	ps
		Measured at 66.67 MHz, loaded outputs, 30-pF load	–	–	200	ps
		Measured at 133.3 MHz, loaded outputs, 15-pF load	–	–	100	ps
t_J	Cycle-to-cycle jitter ^[6] (–2)	Measured at 66.67 MHz, loaded outputs 30-pF load	–	–	400	ps
		Measured at 66.67 MHz, loaded outputs 15-pF load	–	–	375	ps
t_{LOCK}	PLL lock time ^[6]	Stable power supply, valid clocks presented on REF and FBK pins	–	–	1.0	ms

Notes

5. All parameters are specified with loaded output.
6. Parameter is guaranteed by design and characterization. Not 100% tested in production.

Operating Conditions for CY2304SXI Industrial Temperature Devices

Parameter	Description	Min	Max	Unit
V_{DD}	Supply voltage	3.0	3.6	V
T_A	Operating temperature (ambient temperature)	-40	85	°C
C_L	Load capacitance (below 100 MHz)	–	30	pF
	Load capacitance (from 100 MHz to 133 MHz)	–	15	pF
C_{IN}	Input capacitance	–	7	pF

Electrical Characteristics for CY2304SXI Industrial Temperature Devices

Parameter	Description	Test Conditions	Min	Max	Unit
V_{IL}	Input LOW voltage		–	0.8	V
V_{IH}	Input HIGH voltage		2.0	–	V
I_{IL}	Input LOW current	$V_{IN} = 0\text{ V}$	–	50.0	μA
I_{IH}	Input HIGH current	$V_{IN} = V_{DD}$	–	100.0	μA
V_{OL}	Output LOW voltage ^[7]	$I_{OL} = 8\text{ mA}$ (–1, –2)	–	0.4	V
V_{OH}	Output HIGH voltage ^[7]	$I_{OH} = -8\text{ mA}$ (–1, –2)	2.4	–	V
I_{DD} (PD mode)	Power-down supply current	REF = 0 MHz	–	25.0	μA
I_{DD}	Supply current	Unloaded outputs, 100 MHz, Select inputs at V_{DD} or GND	–	45.0	mA
		Unloaded outputs, 66 MHz REF (–1, –2)	–	35.0	mA
		Unloaded outputs, 33 MHz REF (–1, –2)	–	20.0	mA

Note

7. Parameter is guaranteed by design and characterization. Not 100% tested in production.

Switching Characteristics for CY2304SXI Industrial Temperature Devices

Parameter ^[8]	Name	Test Conditions	Min	Typ.	Max	Unit
t_1	Output frequency	30-pF load, All devices	10	–	100	MHz
t_1	Output frequency	15-pF load, All devices	10	–	133.3	MHz
t_{DC}	Duty cycle ^[9] = $t_2 \div t_1$ (–1, –2)	Measured at 1.4 V, $F_{OUT} = 66.66$ MHz, 30-pF load	40.0	50.0	60.0	%
t_{DC}	Duty cycle ^[9] = $t_2 \div t_1$ (–1, –2)	Measured at 1.4 V, $F_{OUT} < 50$ MHz, 15-pF load	45.0	50.0	55.0	%
t_3	Rise time ^[9] (–1, –2)	Measured between 0.8 V and 2.0 V, 30-pF load	–	–	2.50	ns
t_3	Rise time ^[9] (–1, –2)	Measured between 0.8 V and 2.0 V, 15-pF load	–	–	1.50	ns
t_4	Fall time ^[9] (–1, –2)	Measured between 0.8 V and 2.0 V, 30-pF load	–	–	2.50	ns
t_4	Fall time ^[9] (–1, –2)	Measured between 0.8 V and 2.0 V, 15-pF load	–	–	1.50	ns
t_5	Output-to-output skew on same bank (–1, –2) ^[9]	All outputs equally loaded	–	–	200	ps
	Output bank A to output bank B skew (–1)	All outputs equally loaded	–	–	200	ps
	Output bank A to output bank B skew (–2)	All outputs equally loaded	–	–	400	ps
t_6	Skew, REF rising edge to FBK rising edge ^[9]	Measured at $V_{DD}/2$	–	0	±250	ps
t_7	Device-to-device skew ^[9]	Measured at $V_{DD}/2$ on the FBK pins of devices	–	0	500	ps
t_J	Cycle-to-cycle jitter ^[9] (–1)	Measured at 66.67 MHz, loaded outputs, 15-pF load	–	–	180	ps
		Measured at 66.67 MHz, loaded outputs, 30-pF load	–	–	200	ps
		Measured at 133.3 MHz, loaded outputs, 15-pF load	–	–	100	ps
t_J	Cycle-to-cycle jitter ^[9] (–2)	Measured at 66.67 MHz, loaded outputs, 30-pF load	–	–	400	ps
		Measured at 66.67 MHz, loaded outputs, 15-pF load	–	–	380	ps
t_{LOCK}	PLL lock time ^[9]	Stable power supply, valid clocks presented on REF and FBK pins	–	–	1.0	ms

Notes

8. All parameters are specified with loaded output.
9. Parameter is guaranteed by design and characterization. Not 100% tested in production.

Switching Waveforms

Figure 2. Duty Cycle Timing

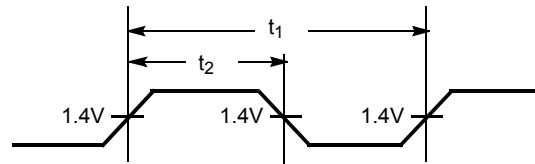


Figure 3. All Outputs Rise/Fall Time

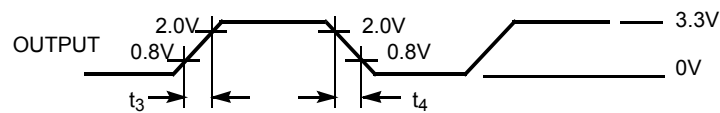


Figure 4. Output-Output Skew

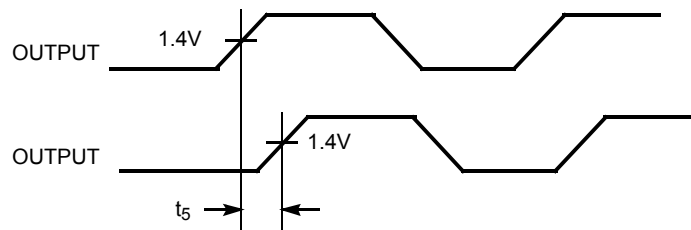


Figure 5. Input-Output Skew

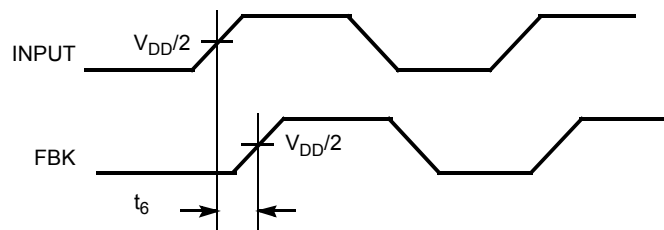


Figure 6. Device-Device Skew

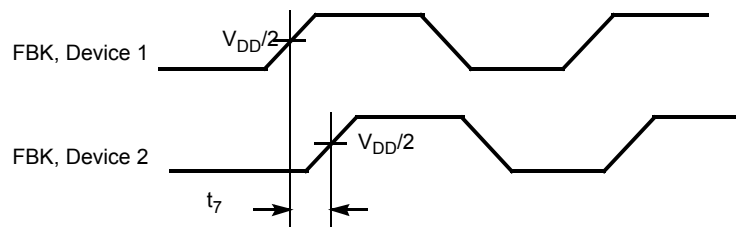
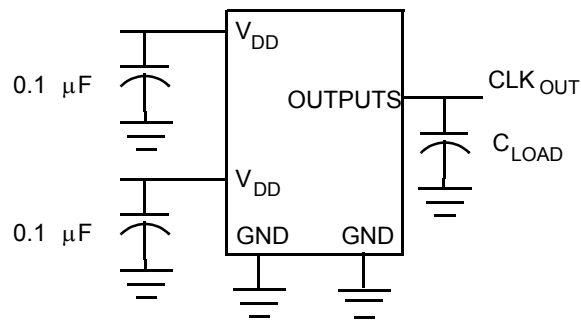


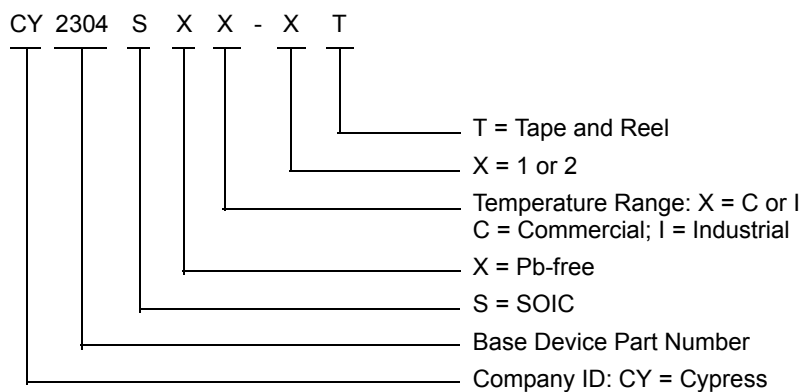
Figure 7. Test Circuit # 1


Test circuit for all parameters

Ordering Information

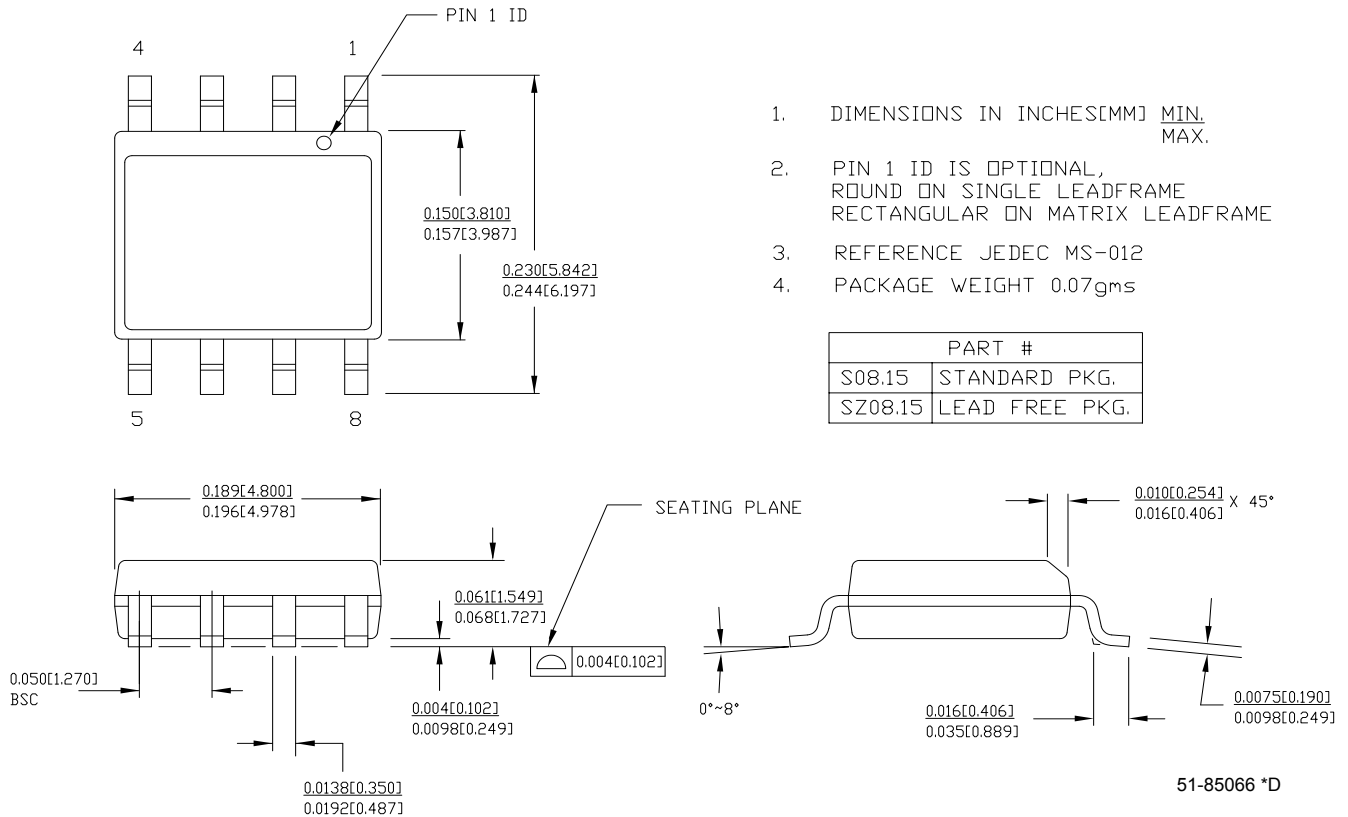
Ordering Code	Package Type	Operating Range
Pb-free		
CY2304SXC-1	8-pin 150-mil SOIC	Commercial
CY2304SXC-1T	8-pin 150-mil SOIC - Tape and Reel	Commercial
CY2304SXI-1	8-pin 150-mil SOIC	Industrial
CY2304SXI-1T	8-pin 150-mil SOIC - Tape and Reel	Industrial
CY2304SXC-2	8-pin 150-mil SOIC	Commercial
CY2304SXC-2T	8-pin 150-mil SOIC - Tape and Reel	Commercial
CY2304SXI-2	8-pin 150-mil SOIC	Industrial
CY2304SXI-2T	8-pin 150-mil SOIC - Tape and Reel	Industrial

Ordering Code Definitions



Package Drawing and Dimensions

Figure 8. 8-pin (150-Mil) SOIC S8



Acronyms

Acronym	Description
PCI	Personal computer interconnect
PLL	Phase locked loop
SDRAM	Synchronous dynamic random access memory
SOIC	Small outline integrated circuit
TSSOP	Thin small outline package
ZDB	Zero delay buffer

Document Conventions

Units of Measure

Symbol	Unit of Measure
°C	degree Celsius
μA	micro Amperes
mA	milli Amperes
ms	milli seconds
MHz	Mega Hertz
ns	nano seconds
pF	pico Farad
ps	pico seconds
V	Volts

Document History Page

Document Title: CY2304 3.3 V Zero Delay Buffer Document Number: 38-07247				
Rev.	ECN	Orig. of Change	Submission Date	Description of Change
**	110512	SZV	12/11/01	Change from Spec number: 38-01010 to 38-07247
*A	112294	CKN	03/04/02	On Pin Configuration Diagram (p.1), swapped CLKA2 and CLKA1
*B	113934	CKN	05/01/02	Added Operating Conditions for CY2304SI-X Industrial Temperature Devices, p. 4
*C	121851	RBI	12/14/02	Power up requirements added to Operating Conditions Information
*D	308436	RGL	01/26/05	Added Lead-free Devices
*E	2542331	AESA	09/18/08	Updated template. Added Note "Not recommended for new designs." Removed part number CY2304SI-2 and CY2304SI-2T. Changed Lead-Free to Pb-Free. Changed IDD (PD mode) from 12.0 to 25.0 μ A. Deleted Duty Cycle parameters for $F_{OUT} < 50.0$ MHz for commercial and industrial devices.
*F	2673353	KVM/PYRS	03/13/09	Reverted IDD (PD mode) and Duty Cycle parameters back to the values in revision *D: Changed IDD (PD mode) from 25 to 12 μ A for commercial devices. Added Duty Cycle parameters for $F_{OUT} < 50.0$ MHz for commercial and industrial devices.
*G	2906571	KVM	04/07/10	Removed parts CY2304SC-1, CY2304SC-1T, CY2304SC-2, CY2304SC-2T, CY2304SI-1, CY2304SI-1T from the ordering information table. Updated Package Diagram.
*H	3072674	BASH	10/27/2010	Corrected part number in all table titles (pages 3 to 5) from CY2304SC-X and CY2304SI-X to CY2304SXC and CY2304SXI. Removed "except t_g " from Figure 7
*I	3162681	BASH	02/04/2011	Updated in new template.

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